



Material Content Data Sheet



Sales Product Name		BCR601		Issued		9. January 2019		
MA#		MA002790566						
Package		PG-DSO-8-47		Weight*		80.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.404	0.50	0.50	5042	5042
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		105	
	non noble metal	zinc	7440-66-6	0.034	0.04		420	
	non noble metal	iron	7439-89-6	0.673	0.84		8391	
wires	non noble metal	copper	7440-50-8	27.330	34.07	34.96	340716	349632
	noble metal	palladium	7440-05-3	0.001	0.00		11	
	non noble metal	copper	7440-50-8	0.087	0.11	0.11	1090	1101
encapsulation	organic material	carbon black	1333-86-4	0.152	0.19		1889	
	plastics	epoxy resin	-	4.899	6.11		61072	
	inorganic material	silicondioxide	60676-86-0	45.453	56.68	62.98	566643	629604
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10146	10146
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1117	1117
glue	plastics	acrylic resin	-	0.059	0.07		739	
	noble metal	silver	7440-22-4	0.210	0.26	0.33	2619	3358
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com